Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.015 X .015”**

**.023”**

**.023”**

**For Zener operation, cathode must be operated positive with respect to anode.**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .015” X .015”**

**Backside Potential: Cathode**

**Mask Ref: CZENR-O23**

**APPROVED BY: DK DIE SIZE .023” X .023” DATE: 8/30/21**

**MFG: MICROSEMI/CDI THICKNESS .008” P/N: BZX55C33V**

**DG 10.1.2**

#### Rev B, 7/19/02